



Statement of Compliance

Requested Part

30 March 2013

5221185-9

(Part 1 of 1)

PLUG,75 OHM,COML BNC

Part Status: Active

EU RoHS/ELV Code: Always EU RoHS/ELV Compliant

Solder Process Capability Code: Not applicable for solder process capability

China RoHS:  Restricted Materials Above Threshold

Exemptions: 6(c) - Pb-Alloy in Copper

REACH Oct 2008 SvHC Compliance: Contains no REACH October 2008 SvHC(s)

REACH Jan/Mar 2010 SvHC Compliance: Contains no REACH Jan/Mar 2010 SvHC(s)

REACH June 2010 SvHC Compliance: Contains no REACH June 2010 SvHC(s)

REACH Dec 2010 SvHC Compliance: Contains no REACH December 2010 SvHC(s)

REACH June 2011 SvHC Compliance: Contains no REACH June 2011 SvHC(s)

REACH December 2011 SvHC Compliance: Contains no REACH December 2011 SvHC(s)

REACH June 2012 SvHC Compliance: Not reviewed for REACH June 2012 SvHC(s)

REACH December 2012 SvHC Compliance: Not Reviewed for REACH December 2012 SvHC(s)

Halogen Content: Not Yet Reviewed for halogen content

David R. Bender

Director, Product Compliance

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hex chrome, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to above limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Note that any exemptions taken in this case would not include application specific exemptions (e.g. lead in solder for servers) as TE cannot determine where component products will be used.

Additionally, the part numbers that are identified as 5 of 6 compliant meet the material limits described above, except that these products have lead in the solderable interface only. These products may be suitable for use in an application that has an exemption for the use of lead in solder (e.g. servers, network infrastructure, etc).

Finished electrical and electronic products will be CE marked as required by Directive 2011/65/EU (RoHS2). Components may not be CE marked.

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information provided by our suppliers. This information is subject to change.



30 March 2013

中国电子信息产品环境信息
China EIP Environmental Information



Restricted Materials Above Threshold

电子元件 (Electronic Component) 5221185-9	有毒有害物质或元素 Hazardous Substance					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
电子元件 (Electronic Component)	X	O	O	O	O	O
<p>O: 表示该部件内有有毒有害物质含量在 SJ/T 11363-2006 标准规定的限量要求以下 Indicates that the concentration of the hazardous substance in the part is below the relevant threshold of the SJ/T 1136 3-2006 standard.</p> <p>X: 表示该部件内有有毒有害物质含量超出 SJ/T 11363-2006 标准规定的限量要求 Indicates that the concentration of the hazardous substance in the part is above the relevant threshold of the SJ/T 1136 3-2006 standard.</p>						

Description for part 5221185-9:

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